X-1574 US 10/796,471

PATENT Conf. No.: 2282

IN THE UNITED STATES PATENT OFFICE

Ápplicant:

Leilei Zhang

Assignee:

Xilinx, Inc.

Title:

Metal Lid with Improved Adhesion to Package Substrate

Serial No.:

10/796,471

Filing Date:

March 9, 2004

Examiner:

Jose R. Diaz

Art Unit:

2815

Docket No.: X-1574 US

Conf. No.:

2282

Mail Stop AF Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

STATEMENT OF THE SUBSTANCE OF THE INTERVIEW

Sir:

The undersigned sincerely thanks Examiner Jose R. Diaz for the telephonic interview on November 30, 2006, and submits this Statement of the Substance of the Interview ("Statement") in accordance with 37 C.F.R. § 1.133. This Statement is being filed with a Response to the Final Office Action.

The participants in the telephonic interview were Examiner Jose R. Diaz, and Mr. Scott W. Hewett, attorney for the Applicant.

No exhibit was shown and no demonstration was conducted.

Claim 11 was discussed in light of the objections to the drawings for failure to describe a gap. The enablement of claim 1 was discussed, including reference to U.S. Patent No. 6,654,448 by Fishley et al. Arguments in support of the enablement of claims 1-21, 31, and 31 are included in the Response to the Final Office Action filed herewith. No amendments to the claims were proposed, and no amendments to the claims are made in the Response to the Final Office Action.

The Examiner suggested adding a section line to Fig. 2B to more clearly indicate the cross section represented by Fig. 2A. Fig. 2B and its associated portion of the written description are amended accordingly in the Response to the Final Office

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Action. The Examiner also suggested indicating that the space around the chip capacitors in Fig. 2A is not filled with encapsulant. A reference numeral and lead line is added to Fig. 2A and the written description is amended in the Response to the Final Office Action to indicate this space. Mr. Hewett suggested copying the language of claim 11 into the written description so that the term "gap" was described. The written description is amended to this effect in the Response to the Final Office Action.

No amendments to the claims were proposed, and no agreement regarding the claims was reached. It was agreed that the matters discussed in the interview would be addressed in the Response to the Final Office Action for the Examiner's consideration.

Respectfully Submitted

Scott W. Hewett Reg. No. 41, 836

Scott Hewett Patent Attorney 400 West Third Street, No. 223 Santa Rosa, CA 95401 Tel.: (707) 591-0789

Fax.: (707) 591-0769

Modified 02-03

PTO/SB/21 (01-03)
Approved for use through 9/30/00. OMB 0651-0031
Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE

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TRANSMITTAL		Application / Conf. No.	10/796,471 2282
		Filing Date	March 09, 2004
FORM		First Named Inventor	Leilei Zhang
(to be used for all correspondence after initial filing)		Examiner Name	Jose R. Diaz
Mail Stop: AF		Art Unit	2815
Express Mail Receipt No.		Patent No.	
Total Number of Pages in This Submission		Attorney Docket Number	X-1574 US
ENCLOSURES (check all that apply)			
X Fee Transmittal Form X Amendment / Reply Preliminary Amendment X After Final Affidavit(s)/declaration(s) Extension of Time Request Change Status to LARGE ENTITY Express Abandonment Request X Information Disclosure Statement X Substitute PTO-1449(s) IDS by Applicant (PTO/SB/08A) Certified Copy of Priority Document(s)	Declar Drawir Licens Petition To Con Provisi Power Chang Addres Termir Reque	nvert a ional Application of Attorney, Revocation e of Correspondence	After Allowance Communication to to Appeal Communication to Board of Appeals and Interferences Appeal Communication to Group (Appeal Notice, Brief, Reply Brief) Status Letter X Return Receipt Postcard X Other Enclosure(s) (please identify below): One reference; Statement of the Substance of the Interview
Response to Missing Parts/ Incomplete Application Response to Missing Parts under 37 CFR 1.52 or 1.53	Remarks	!	
SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT			
Firm or Customer Number Attn: Michael RA Hard Signature	Michael R. Hardaway		Reg. Number 52,992 fees required/credit any overpayment
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Typed or Printed Name Pat Tompkins			
Signature Col Tompile Date December 13, 2006			

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